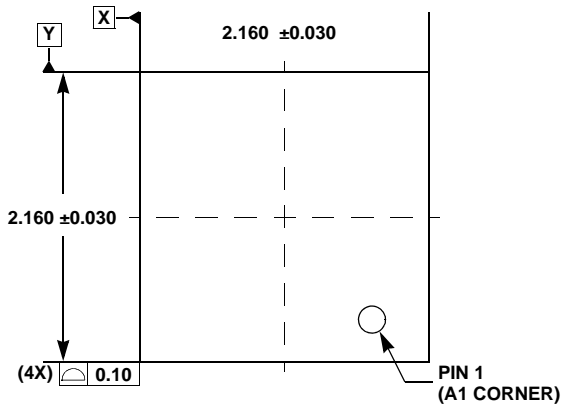


Package Outline Drawing

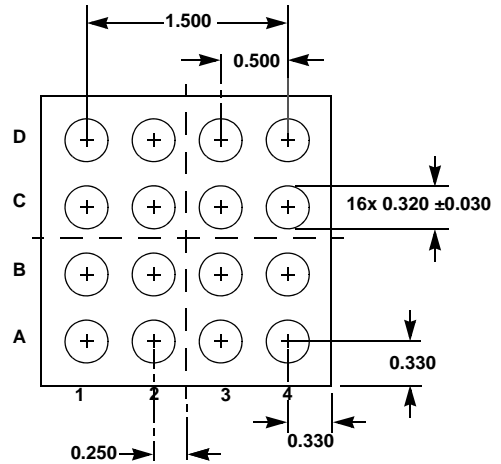
W4x4.16C

(WLCSP 0.5mm PITCH) WAFER LEVEL CHIP SCALE PACKAGE

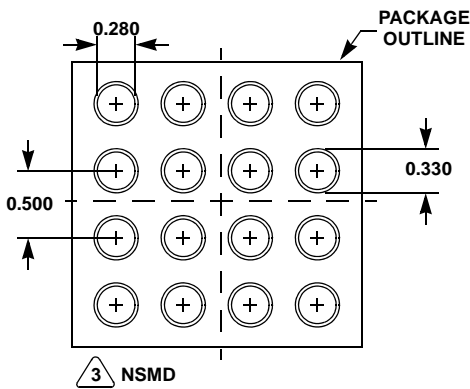
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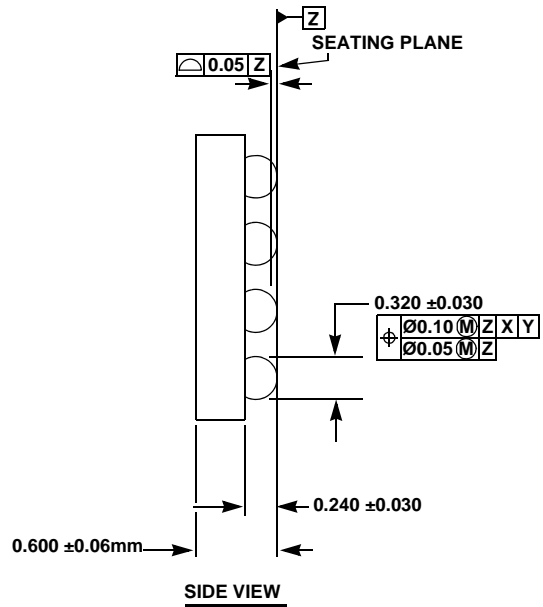
TOP VIEW



BOTTOM VIEW



RECOMMENDED LAND PATTERN



SIDE VIEW

NOTES:

1. All dimensions are in millimeters.
2. Dimension and tolerance per ASMEY 14.5M-1994, and JESD 95-1 SPP-010.
3. NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).